

# 74LVT14

## 3.3 V hex inverter Schmitt trigger

Rev. 02 — 25 April 2008

Product data sheet

### 1. General description

The 74LVT14 is a high-performance BiCMOS product designed for  $V_{CC}$  operation at 3.3 V. It is capable of transforming slowly changing input signals into sharply defined, jitter free output signals. In addition, it has a greater noise margin than conventional inverters.

Each circuit contains a Schmitt trigger followed by a Darlington level shifter and a phase splitter driving a TTL totem-pole output. The Schmitt trigger uses positive feedback to effectively speed-up slow input transitions, and provide different input threshold voltages for positive-going and negative-going inputs. The threshold differential (typically 600 mV) is determined internally by resistor ratios and is insensitive to temperature and supply voltage variations.

### 2. Features

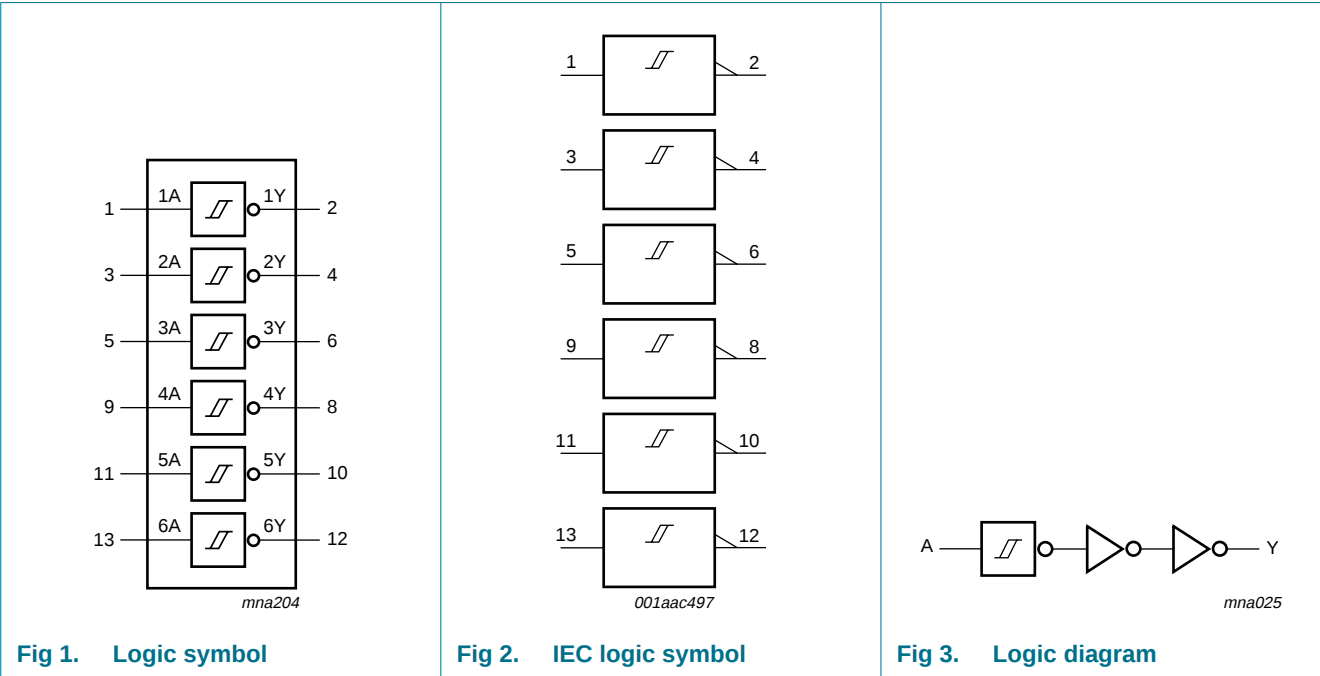
- Different positive and negative going input threshold voltages
- Tolerant of slow input transitions
- High noise immunity
- TTL input and output switching levels
- Output capability: +32 mA/–20 mA
- Latch-up protection exceeds 500 mA per JESD78 class II level A
- ESD protection:
  - ◆ HBM JESD22-A114E exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V

### 3. Ordering information

Table 1. Ordering information

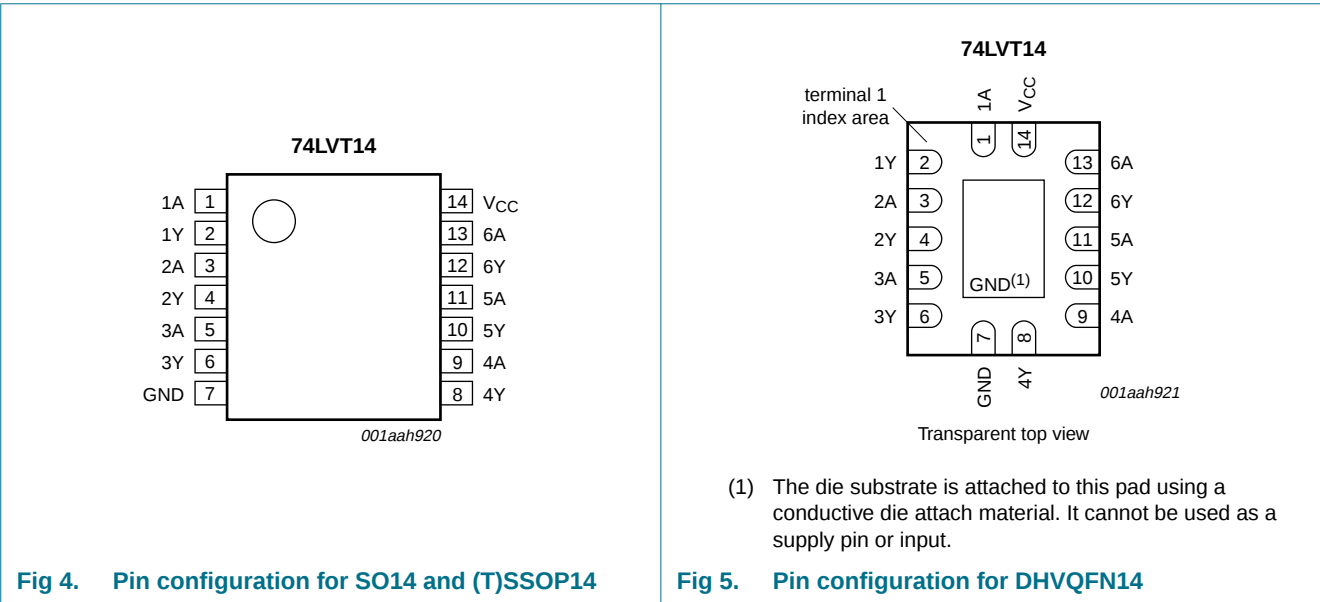
| Type number | Package           |          |                                                                                                                                      |          |
|-------------|-------------------|----------|--------------------------------------------------------------------------------------------------------------------------------------|----------|
|             | Temperature range | Name     | Description                                                                                                                          | Version  |
| 74LVT14D    | –40 °C to +85 °C  | SO14     | plastic small outline package; 14 leads;<br>body width 7.5 mm                                                                        | SOT108-1 |
| 74LVT14DB   | –40 °C to +85 °C  | SSOP14   | plastic shrink small outline package; 14 leads;<br>body width 5.3 mm                                                                 | SOT337-1 |
| 74LVT14PW   | –40 °C to +85 °C  | TSSOP14  | plastic thin shrink small outline package; 14 leads;<br>body width 4.4 mm                                                            | SOT402-1 |
| 74LVT14BQ   | –40 °C to +85 °C  | DHVQFN14 | plastic dual in-line compatible thermal enhanced very<br>thin quad flat package; no leads; 14 terminals;<br>body 2.5 × 4.5 × 0.85 mm | SOT762-1 |

4. Functional diagram



5. Pinning information

5.1 Pinning



## 5.2 Pin description

**Table 2.** Pin description

| Symbol          | Pin                | Description             |
|-----------------|--------------------|-------------------------|
| 1A to 6A        | 1, 3, 5, 9, 11, 13 | data input              |
| 1Y to 6Y        | 2, 4, 6, 8, 10, 12 | data output             |
| GND             | 7                  | ground (0 V)            |
| V <sub>CC</sub> | 14                 | positive supply voltage |

## 6. Functional description

**Table 3.** Function selection

| Inputs | Output |
|--------|--------|
| nA     | nY     |
| L      | H      |
| H      | L      |

- [1] H = HIGH voltage level;  
L = LOW voltage level.

## 7. Limiting values

**Table 4.** Limiting values [1]

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol           | Parameter               | Conditions                          | Min      | Max  | Unit |
|------------------|-------------------------|-------------------------------------|----------|------|------|
| V <sub>CC</sub>  | supply voltage          |                                     | -0.5     | +4.6 | V    |
| V <sub>I</sub>   | input voltage           |                                     | [2] -0.5 | +7.0 | V    |
| V <sub>O</sub>   | output voltage          | output in OFF or HIGH state         | [2] -0.5 | +7.0 | V    |
| I <sub>IK</sub>  | input clamping current  | V <sub>I</sub> < 0 V                | -50      | -    | mA   |
| I <sub>OK</sub>  | output clamping current | V <sub>O</sub> < 0 V                | -50      | -    | mA   |
| I <sub>O</sub>   | output current          | output in LOW state                 | -        | 64   | mA   |
|                  |                         | output in HIGH state                | -32      | -    | mA   |
| T <sub>stg</sub> | storage temperature     |                                     | -65      | +150 | °C   |
| T <sub>j</sub>   | junction temperature    |                                     |          | +150 | °C   |
| P <sub>tot</sub> | total power dissipation | T <sub>amb</sub> = -40 °C to +85 °C | [3]      | 500  | mW   |

- [1] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.
- [2] The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
- [3] For SO14 packages: above 70 °C derate linearly with 8 mW/K.  
For SSOP14 and TSSOP14 packages: above 60 °C derate linearly with 5.5 mW/K.  
For DHVQFN14 packages: above 60 °C derate linearly with 4.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

| Symbol           | Parameter                           | Conditions     | Min | Typ | Max | Unit |
|------------------|-------------------------------------|----------------|-----|-----|-----|------|
| V <sub>CC</sub>  | supply voltage                      |                | 2.7 | -   | 3.6 | V    |
| V <sub>I</sub>   | input voltage                       |                | 0   | -   | 5.5 | V    |
| I <sub>OH</sub>  | HIGH-level output current           |                | -20 | -   | -   | mA   |
| I <sub>OL</sub>  | LOW-level output current            |                | -   | -   | 32  | mA   |
| T <sub>amb</sub> | ambient temperature                 | in free air    | -40 | -   | +85 | °C   |
| Δt/ΔV            | input transition rise and fall rate | output enabled | 0   | -   | 10  | ns/V |

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

| Symbol           | Parameter                        | Conditions                                                                                                                        | -40 °C to +85 °C      |                    |      | Unit |
|------------------|----------------------------------|-----------------------------------------------------------------------------------------------------------------------------------|-----------------------|--------------------|------|------|
|                  |                                  |                                                                                                                                   | Min                   | Typ <sup>[1]</sup> | Max  |      |
| V <sub>T+</sub>  | positive-going threshold voltage | V <sub>CC</sub> = 3.3 V; see <a href="#">Figure 7</a>                                                                             | 1.5                   | 1.7                | 2.0  | V    |
| V <sub>T-</sub>  | negative-going threshold voltage | V <sub>CC</sub> = 3.3 V; see <a href="#">Figure 7</a>                                                                             | 0.9                   | 1.1                | 1.3  | V    |
| V <sub>H</sub>   | hysteresis voltage               | V <sub>CC</sub> = 3.3 V; see <a href="#">Figure 7</a>                                                                             | 0.4                   | 0.6                | -    | V    |
| V <sub>IK</sub>  | input clamping voltage           | V <sub>CC</sub> = 2.7 V; I <sub>IK</sub> = -18 mA                                                                                 | -1.2                  | -                  | -    | V    |
| V <sub>IH</sub>  | HIGH-level input voltage         |                                                                                                                                   | 2.0                   | -                  | -    | V    |
| V <sub>IL</sub>  | LOW-level input voltage          |                                                                                                                                   | -                     | -                  | 0.8  | V    |
| V <sub>OH</sub>  | HIGH-level output voltage        | V <sub>CC</sub> = 2.7 V to 3.6 V; I <sub>OH</sub> = -100 μA                                                                       | V <sub>CC</sub> - 0.2 | -                  | -    | V    |
|                  |                                  | V <sub>CC</sub> = 2.7 V; I <sub>OH</sub> = -6 mA                                                                                  | 2.4                   | -                  | -    | V    |
|                  |                                  | V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -20 mA                                                                                 | 2.0                   | -                  | -    | V    |
| V <sub>OL</sub>  | LOW-level output voltage         | V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 100 μA                                                                                 | -                     | -                  | 0.2  | V    |
|                  |                                  | V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 24 mA                                                                                  | -                     | -                  | 0.5  | V    |
|                  |                                  | V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 32 mA                                                                                  | -                     | -                  | 0.5  | V    |
| I <sub>I</sub>   | input leakage current            | V <sub>CC</sub> = 0 V or 3.6 V; V <sub>I</sub> = 5.5 V                                                                            | -                     | -                  | 10   | μA   |
|                  |                                  | V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>CC</sub> or GND                                                                  | -                     | -                  | ±1   | μA   |
| I <sub>OFF</sub> | power-off leakage current        | V <sub>CC</sub> = 0 V; V <sub>I</sub> or V <sub>O</sub> = 0 V to 4.5 V                                                            | -                     | -                  | ±100 | μA   |
| I <sub>CC</sub>  | supply current                   | V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A                                           |                       |                    |      |      |
|                  |                                  | outputs HIGH                                                                                                                      | -                     | -                  | 0.02 | mA   |
|                  |                                  | outputs LOW                                                                                                                       | -                     | 1.5                | 3    | mA   |
| ΔI <sub>CC</sub> | additional supply current        | per input pin; V <sub>CC</sub> = 3.0 V to 3.6 V;<br>one input = V <sub>CC</sub> - 0.6 V<br>other inputs at V <sub>CC</sub> or GND | <sup>[2]</sup> -      | -                  | 0.2  | mA   |
| C <sub>I</sub>   | input capacitance                | V <sub>I</sub> = 0 V or 3.0 V                                                                                                     | -                     | 3                  | -    | pF   |

[1] All typical values are measured at V<sub>CC</sub> = 3.3 V (unless stated otherwise) and T<sub>amb</sub> = 25 °C.

[2] This is the increase in the supply current for each input at the specified voltage level other than V<sub>CC</sub> or GND.

10. Dynamic characteristics

Table 7. Dynamic characteristics
Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 8.

| Symbol           | Parameter                     | Conditions                      | −40 °C to +85 °C |        |     | Unit |
|------------------|-------------------------------|---------------------------------|------------------|--------|-----|------|
|                  |                               |                                 | Min              | Typ[1] | Max |      |
| t <sub>PLH</sub> | LOW to HIGH propagation delay | nA to nY                        |                  |        |     |      |
|                  |                               | V <sub>CC</sub> = 2.7 V         | -                | -      | 6.9 | ns   |
|                  |                               | V <sub>CC</sub> = 3.3 V + 0.3 V | 1.0              | 3.8    | 5.7 | ns   |
| t <sub>PHL</sub> | HIGH to LOW propagation delay | nA to nY                        |                  |        |     |      |
|                  |                               | V <sub>CC</sub> = 2.7 V         | -                | -      | 4.1 | ns   |
|                  |                               | V <sub>CC</sub> = 3.3 V + 0.3 V | 1.0              | 3.2    | 4.5 | ns   |

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>CC</sub> = 3.3 V.

11. Waveforms

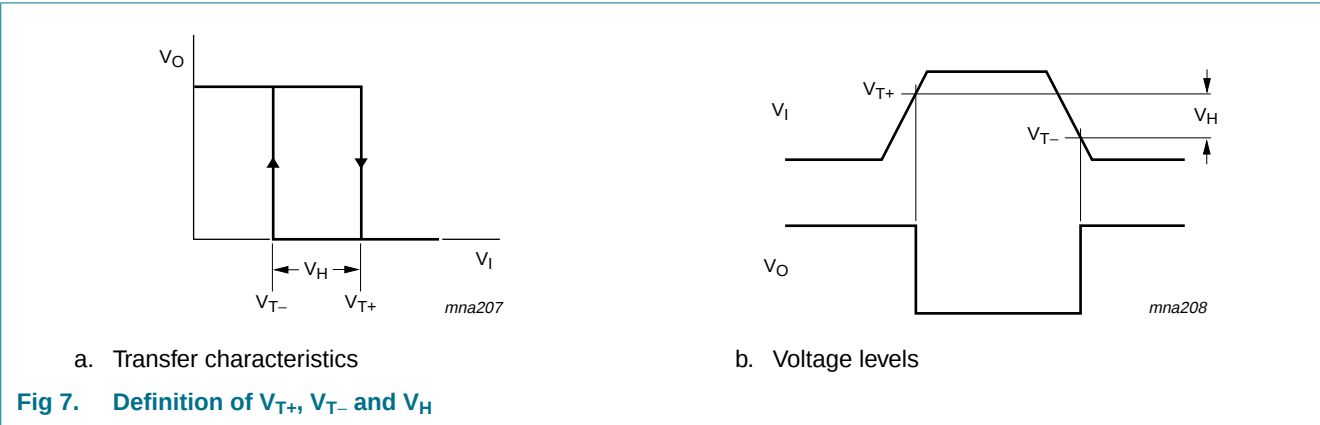
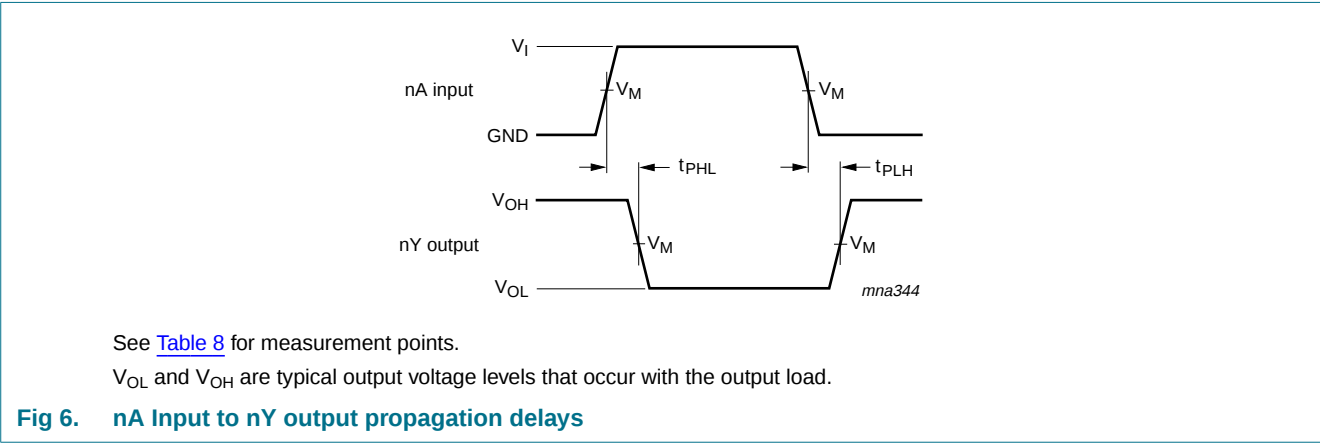
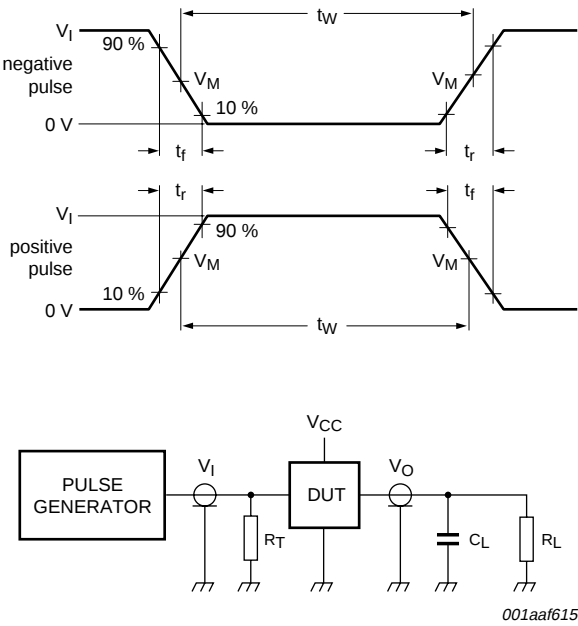


Table 8. Measurement points

| V <sub>CC</sub> | Input          | Output         |
|-----------------|----------------|----------------|
|                 | V <sub>M</sub> | V <sub>M</sub> |
| 2.7 V to 3.6 V  | 1.5 V          | 1.5 V          |



Test data is given in given in [Table 9](#).

Definitions for test circuit:

R<sub>L</sub> = Load resistance;

C<sub>L</sub> = Load capacitance including jig and probe capacitance;

R<sub>T</sub> = Termination resistance should be equal to output impedance Z<sub>o</sub> of the pulse generator.

Fig 8. Load circuitry for switching times

Table 9. Test data

| Supply          | Input pulse requirements |                 |                |                                 |  | Load           |                |
|-----------------|--------------------------|-----------------|----------------|---------------------------------|--|----------------|----------------|
| V <sub>CC</sub> | V <sub>I</sub>           | Repetition rate | t <sub>W</sub> | t <sub>r</sub> , t <sub>f</sub> |  | R <sub>L</sub> | C <sub>L</sub> |
| 2.7 V to 3.3 V  | 2.7 V                    | ≤ 10 MHz        | 500 ns         | ≤ 2.5 ns                        |  | 500 Ω          | 50 pF          |

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm SOT108-1

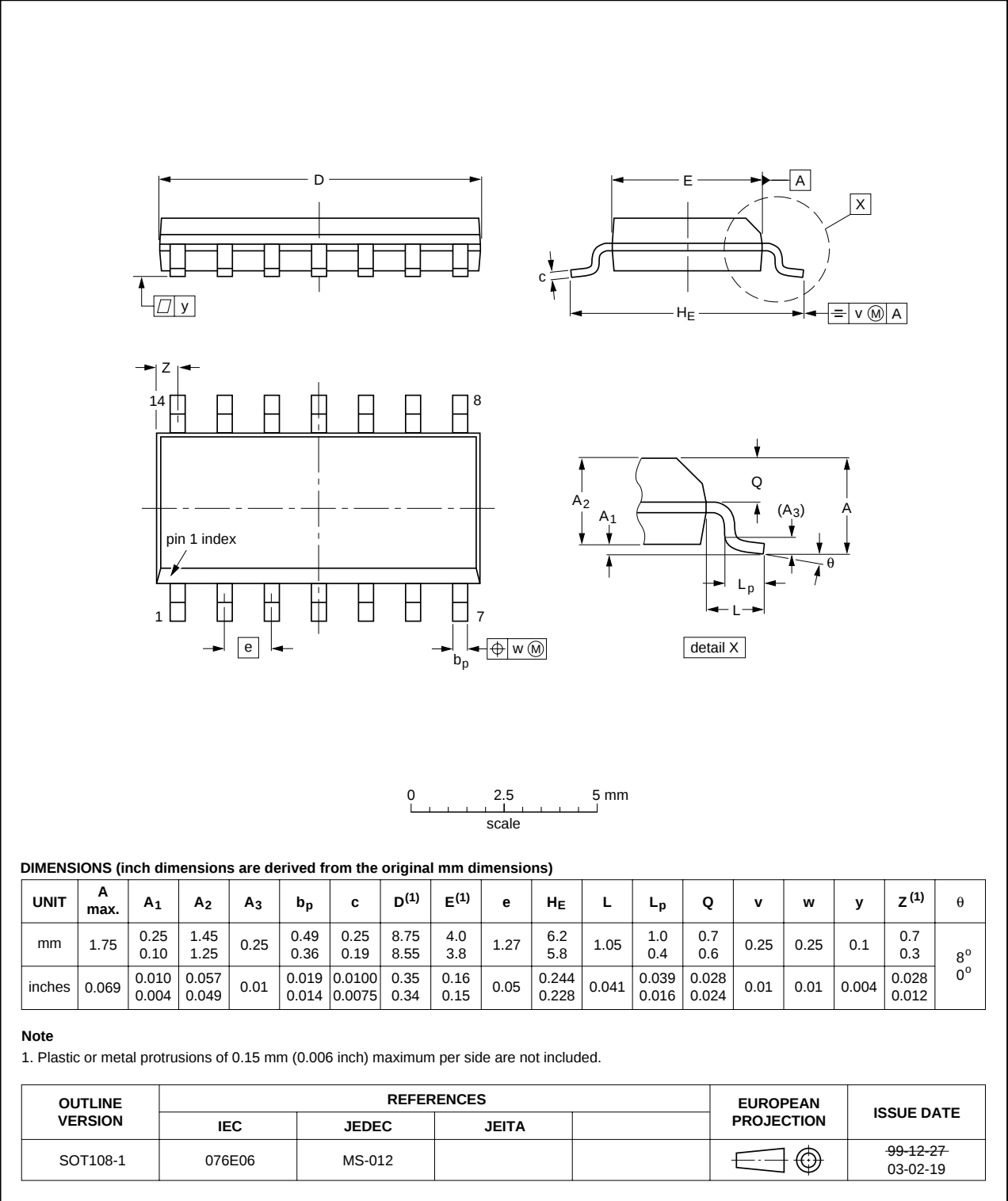


Fig 9. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

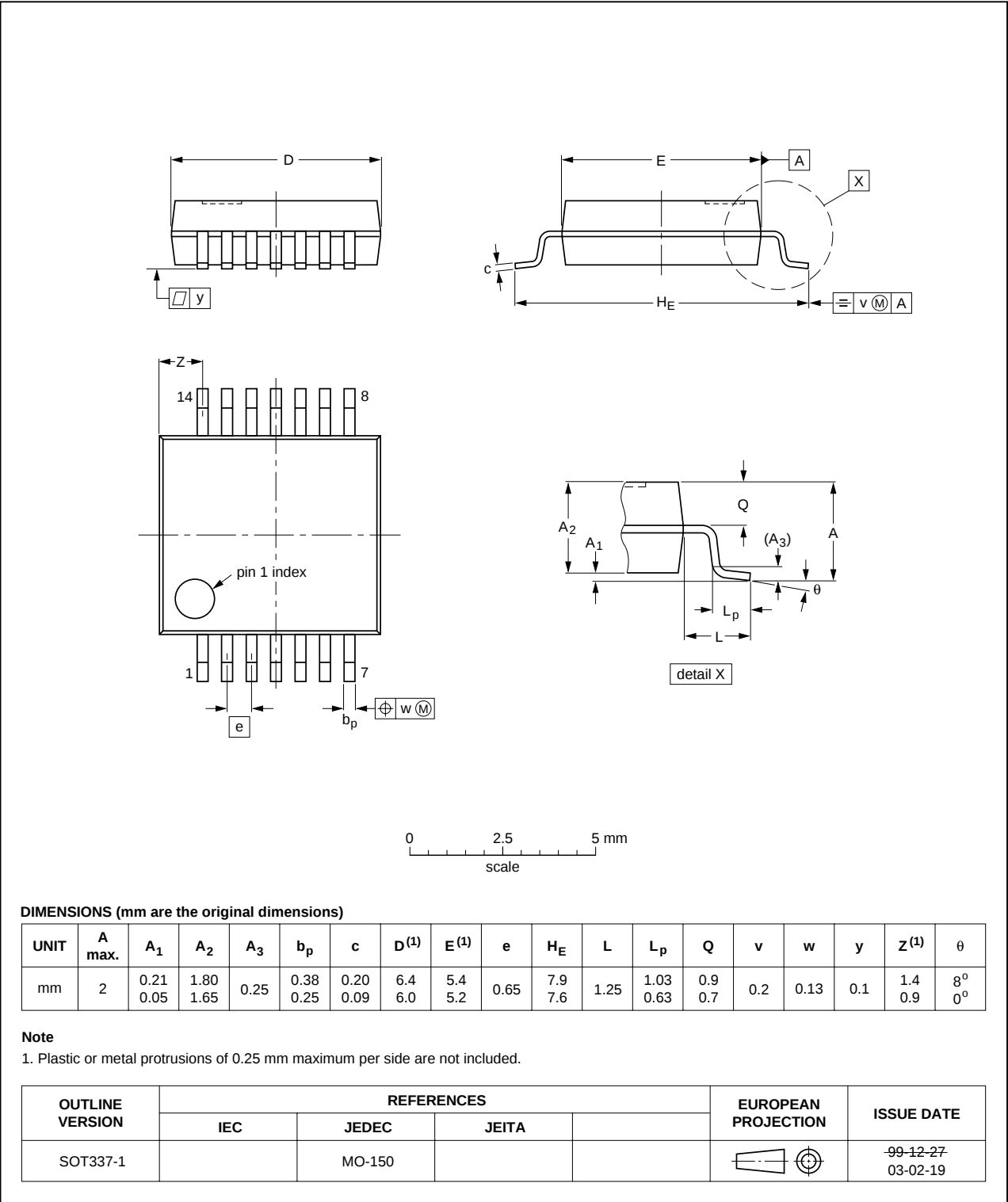


Fig 10. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

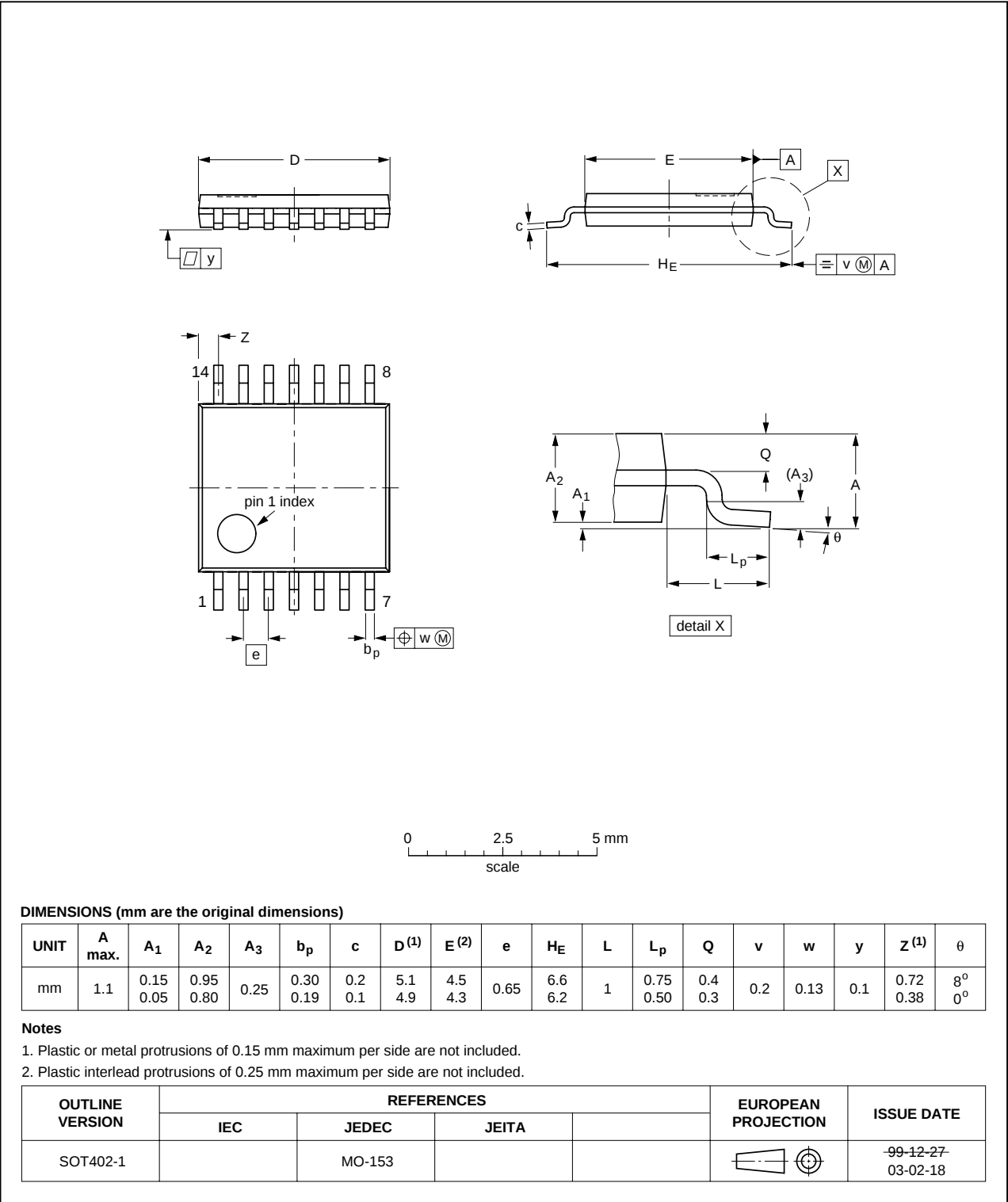


Fig 11. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;  
14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

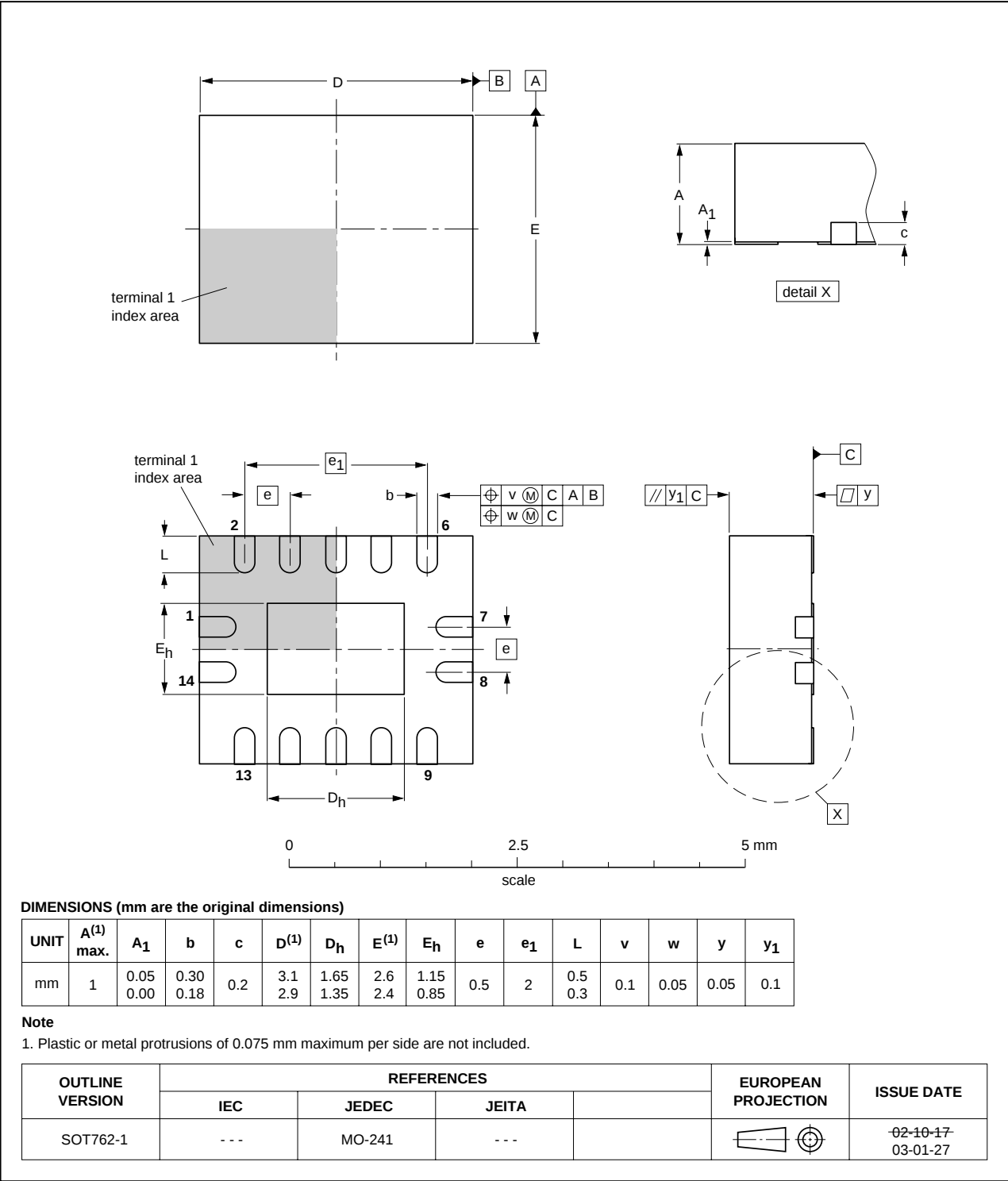


Fig 12. Package outline SOT762-1 (DHVQFN14)

## 13. Abbreviations

Table 10. Abbreviations

| Acronym | Description                                      |
|---------|--------------------------------------------------|
| BICMOS  | Integrated Bipolar junction transistors and CMOS |
| DUT     | Device Under Test                                |
| ESD     | ElectroStatic Discharge                          |
| HBM     | Human Body Model                                 |
| TTL     | Transistor-Transistor Logic                      |

## 14. Revision history

Table 11. Revision history

| Document ID    | Release date                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           | Data sheet status     | Change notice | Supersedes |
|----------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------|---------------|------------|
| 74LVT14_2      | 20080425                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               | Product data sheet    | -             | 74LVT14_1  |
| Modifications: | <ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li><li>• Quick reference section removed.</li><li>• DHVQFN14 package added to <a href="#">Section 3 "Ordering information"</a> and <a href="#">Section 12 "Package outline"</a>.</li><li>• <a href="#">Section 13 "Abbreviations"</a> added.</li></ul> |                       |               |            |
| 74LVT14_1      | 19960828                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               | Product specification | -             | -          |

## 15. Legal information

### 15.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition                                                                            |
|-----------------------------------|-------------------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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